

pSEMI MATERIAL DECLARATION FORM

Product:	PE64906
Ordering Codes:	PE649064B-Z
Description:	UltraCMOS® Digitally Tunable Capacitor (DTC) 100-3000 MHz
Package:	6L 1.5 X 1.5 DFN
Environmental Compliance	EU RoHS2 Directive 2011/65/EC, REACH - EU ECHA SVHC, Arsenic Free , JIG 101 - EIA/EICTA/JEITA, Halogen Free - IEC61249-2-21, PFOS Free - 2006/122/EC, Antimony Trioxide Free
Lead Finish	NiPdAu
Availability	Now

Component	Material	CAS Number	Weight (mg)	%	PPM
Die	Aluminum oxide	1344-28-1	0.782399	8.68%	86,815
Die	Aluminum	7429-90-5	0.002380	0.03%	264
Die	Silicon	7440-21-3	0.000159	0.00%	18
Die	Arsenic*	7440-38-2	0.000001	0.00%	0
Die	Boron*	7440-42-8	0.000000	0.00%	0
Die	Phosphorous*	7723-14-0	0.000003	0.00%	0
Die	Titanium	7440-32-6	0.000397	0.00%	44
Die	Tungsten	7440-33-7	0.007933	0.09%	880
Die	Cobalt	7440-48-4	0.000016	0.00%	2
Die	Copper	7440-50-8	0.000006	0.00%	1
Leadframe	Copper	7440-50-8	4.745000	52.65%	526,503
Leadframe	Nickel	7440-02-0	0.148000	1.64%	16,422
Leadframe	Silicon	7440-21-3	0.032000	0.36%	3,551
Leadframe	Magnesium	7439-95-4	0.007000	0.08%	777
Plating	Nickel	7440-02-0	0.124000	1.38%	13,759
Plating	Palladium	7440-05-3	0.004000	0.04%	444
Plating	Gold	7440-57-5	0.003000	0.03%	333
Die Attach	Acrylates	Proprietary	0.019000	0.21%	2,108
Die Attach	Silver	7440-22-4	0.116000	1.29%	12,871
Die Attach	Proprietary Bismaleimide	Proprietary	0.004000	0.04%	444
Die Attach	Methacrylate ester	Trade secret	0.004000	0.04%	444
Die Attach	Proprietary polymer	Trade secret	0.001000	0.01%	111
Gold Wire	Copper	7440-57-5	0.016000	0.18%	1,775
Mold Compound	Silica fused	60676-86-0	2.577000	28.59%	285,943
Mold Compound	Multi-aromatic resin	Trade secret	0.419000	4.65%	46,492
Total Weight (mg)			9.012293	100.00%	1,000,000